

规格书编号

SPEC NO:

产品规格书

SPECIFICATION

CUSTOMER 客户: _____

PRODUCT 产品: _____ SAW FILTER _____

MODEL NO 型号: _____ HDF785A3-F11 _____

MARKING 印字: _____ HDF785 _____

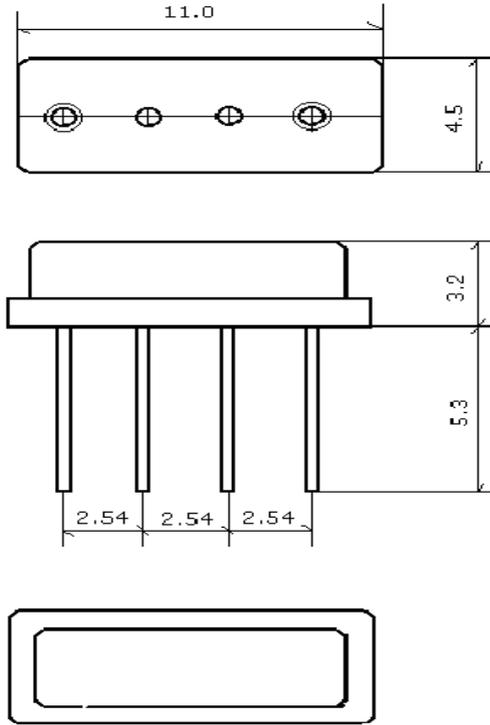
PREPARED 编制: _____ CHECKED 审核: _____

APPROVED 批准: _____ D A T E 日期: _____ 2012-10-15 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. Package Dimension



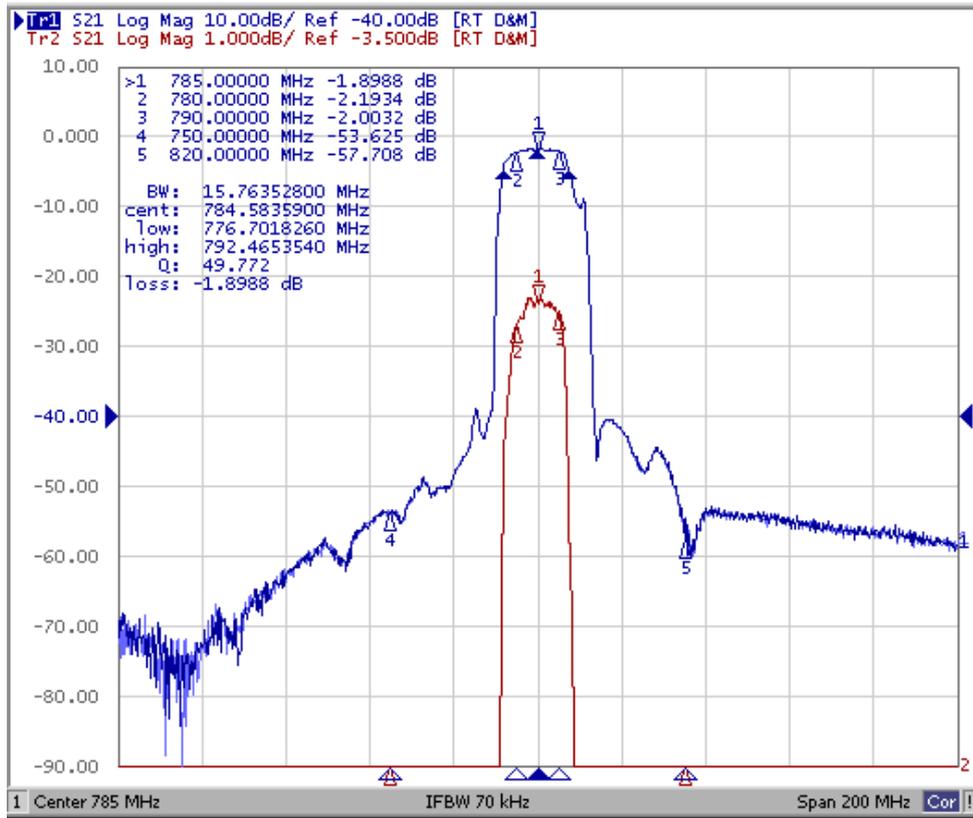
2. Performance

2.1 Maximum Rating

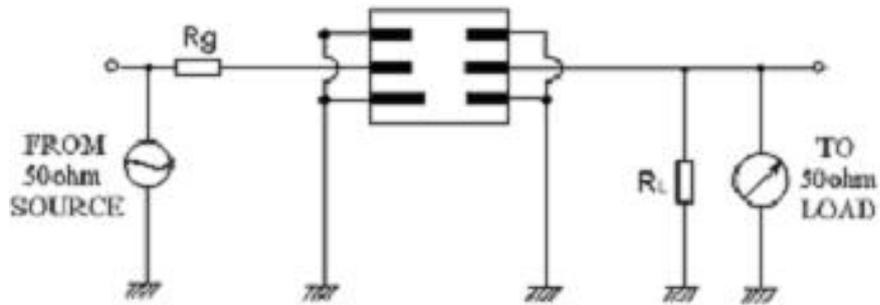
DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-45°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Level	10dBm

2.2 Electronic Characteristics

	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	785	-
Insertion Loss (780~790MHz)	dB		2.2	4.0
Amplitude Ripple (780~790MHz)	dB		0.5	2.0
VSWR(780~790MHz)			1.5	-
Relative Attenuation				
0~750 MHz	dB	40	55	-
820~1300MHz		40	55	
Input/Output Impedance	Ohms		50	



3. TEST CIRCUIT



4. ENVIRONMENTAL CHARACTERISTICS

4-1 Temperature cycling

Subject the device to a low temperature of -45°C for 30 minutes. Following by a high temperature of +25°C for 5 Minutes and a higher temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 3.3.

4-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260°C ± 5°C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 3.3.

4-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 3.3.

4-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 3.3.

4-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 3.3.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.